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JX Advanced Metals Corporation

Toho Titanium to Expand Production Capacity for Ultra-Fine Nickel Powder Used in MLCCs for AI Data Centers

Toho Titanium Co., Ltd. (“Toho Titanium,” President: Hyakuno Manabu), a group company of JX Advanced Metals Corporation (“JX Advanced Metals,” President: Hayashi Yoichi), has decided to expand its production capacity for smaller-particle-size ultra-fine nickel powder used in multilayer ceramic capacitors (MLCCs). Toho Titanium plans to phase the new equipment into operation at its Chigasaki Plant (Chigasaki City, Kanagawa Prefecture) beginning in 2027, doubling its production capacity for smaller-particle-size products. The company will subsequently expand its supply capacity in stages in line with demand trends.

In recent years, the rapid adoption of generative AI has driven the construction of AI data centers worldwide, resulting in growing demand for the electronic components that high-performance servers and peripheral equipment require. High-end MLCCs, in particular, must combine smaller size and higher capacitance with a high degree of reliability. Accordingly, demand is also increasing for finer and more consistent nickel powder used as an internal electrode material.

Toho Titanium manufactures ultra-fine nickel powder at its Chigasaki Plant and Wakamatsu Plant (Kitakyushu City, Fukuoka Prefecture). By applying the proprietary production technology it has derived from its titanium smelting expertise, Toho Titanium is able to manufacture ultra-fine nickel powder with a narrow particle size distribution. Its ultra-fine nickel powder is used in the internal electrodes of high-end MLCCs.

To meet the anticipated growth in demand from AI data centers and other applications, Toho Titanium will expand the facilities at its Chigasaki Plant and strengthen its mass-production capabilities for smaller-particle-size ultra-fine nickel powder.

The JX Advanced Metals Group provides a diverse range of advanced materials that support AI data centers and advanced semiconductors, including sputtering targets for semiconductors, indium phosphide substrates, and ultra-fine nickel powder for MLCCs. Through this capacity expansion, the Group will further strengthen its ability to ensure a stable supply to the growing high-end MLCC market. By supplying materials that are essential to cutting-edge devices, the Group will continue contributing to social progress and innovation.

Reference

For more information on Toho Titanium’s ultra-fine nickel powder, please visit [the product page](#).